

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



6 PIN, BT QFN CASE 485AD ISSUE A

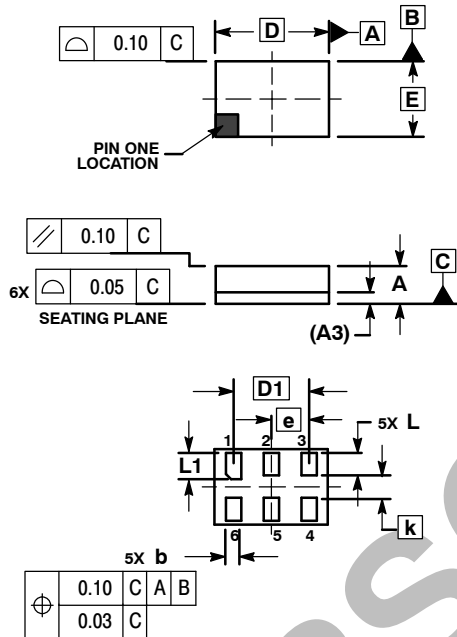
DATE 18 NOV 2019



SCALE 4:1

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



MILLIMETERS		
DIM	MIN	MAX
A	0.450	0.550
A3	0.150 BSC	
D	1.500 BSC	
D1	1.000 BSC	
E	1.000 BSC	
b	0.150	0.250
e	0.500 BSC	
L	0.250	0.350
L1	0.300	0.400
k	0.300 BSC	

GENERIC MARKING DIAGRAM*



- xx = Specific Device Code
- A = Assembly Location
- WL, L = Wafer Lot
- YY, Y = Year
- WW, W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking.

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NEW STANDARD:		
DESCRIPTION:	6 PIN, BT QFN	PAGE 1 OF 2

